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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 16231A**

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**Issue Date:** 1-Mar-2013

**TITLE:** Copper wire bond for NCP1117LP family for the IC SOT223 package

**PROPOSED FIRST SHIP DATE:** 1-Jun-2013

**AFFECTED CHANGE CATEGORY(S):** Assembly Process

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or <[alan.garlington@onsemi.com](mailto:alan.garlington@onsemi.com)>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or <[tomas.vajter@onsemi.com](mailto:tomas.vajter@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

FPCN #16231 was issued on March 12, 2009 to begin using Copper wire on the IC SOT223 assembly line located in Seremban, Malaysia. The line has now been in production for several years using the Copper process. A new device was introduced shortly after the original FPCN was issued and was not included on the original FPCN.

The purpose of this FPCN is to add this one device family to the list of qualified products using the Copper Process. At the expiration of this FPCN, the below listed parts may be supplied with either Gold (Au) or Copper (Cu) wire bonds.



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**RELIABILITY DATA SUMMARY:**

Test Vehicles used: NCP565ST12T3G and NCP1117STAT3G

**Reliability Test Results: NCP565ST12T3G**

<b>Test</b>	<b>Conditions</b>	<b>Results</b>
HTSL High Temp Storage Life	Ta = 150c ; 1000 Hrs	0/168
UHASt-PC Highly Accel. Stress Test	Ta = 130C, RH = 85%; 96 Hrs	0/168
Preconditioned PSIG = 18.8, with bias TC – PC Temperature Cycle	-65C to +150C; 1000 Cycle	0/168
Preconditioned MSL1 SAT Testing MSL1 Preconditioning		0/10

**Reliability Test Results: NCP1117STAT3G**

<b>Test</b>	<b>Conditions</b>	<b>Results</b>
HTSL High Temp Storage Life	Ta = 150c; 1000 Hrs	0/168
UHASt-PC Highly Accel. Stress Test	Ta = 130C, RH = 85%; 96 Hrs	0/168
Preconditioned PSIG = 18.8, with bias TC – PC Temperature Cycle	-65C to +150C; 1000 Cycle	0/168
Preconditioned MSL1 SAT Testing MSL1 Preconditioning		0/10

**ELECTRICAL CHARACTERISTIC SUMMARY:**

Electrical Data is available upon request.

**CHANGED PART IDENTIFICATION:**

Part Number Date Code with codes greater than WW 23, 2013

**List of affected General Parts:**

- NCP1117LPST15T3G
- NCP1117LPST18T3G
- NCP1117LPST25T3G
- NCP1117LPST33T3G
- NCP1117LPST50T3G
- NCP1117LPSTADT3G